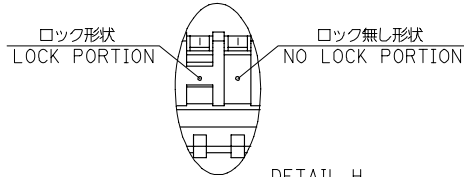
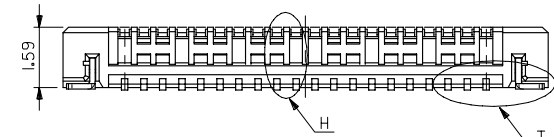
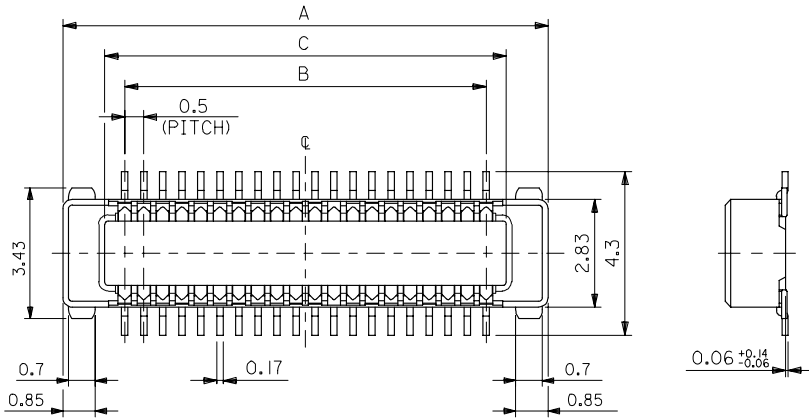


注記
NOTES:

1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
銅メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 54363-****
MATED CONN.: 54363-****
5. 本製品は55650-***1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***1

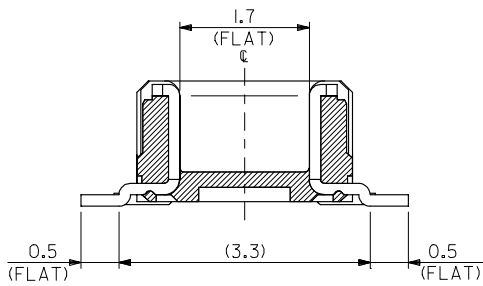


DETAIL H
SCALE 2:1

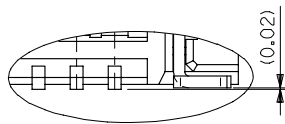
—#	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-***1

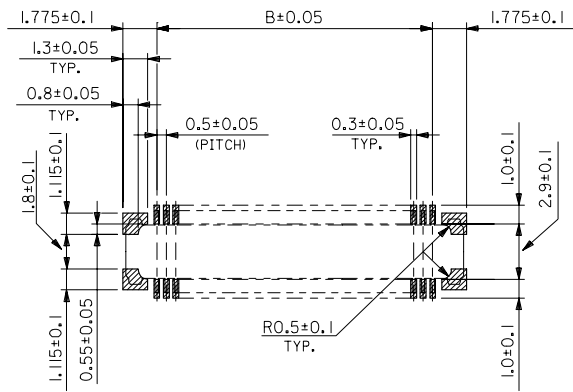
REVISED EC NO: J2008-0540 DRAWN: AOHYAGI 2007/09/03 CHKD: KUYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-013		
	ANGULAR ±3 °	MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3		EN-02JA(021)			



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
T部図詳細

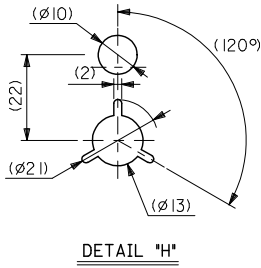
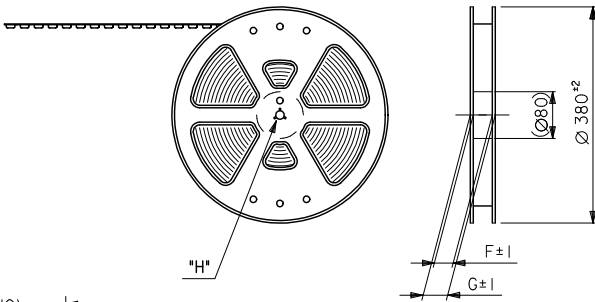


推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)

REVISED EC NO: J2008-0540 2007/09/03 DRWN: YAOYAGI CHKD: KUYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-013		
	ANGULAR	±3 °	MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

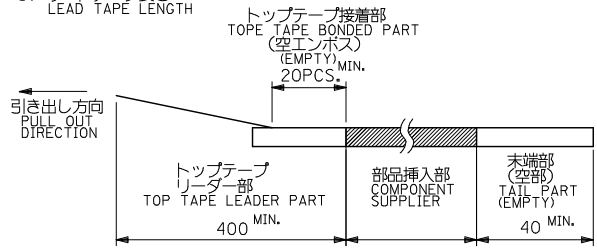
10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION



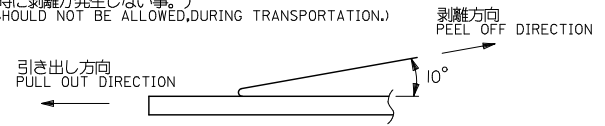
注)
NOTES

1. 製品番号55650-***81詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55650-***81 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量:2500個/リール
NUMBER OF CONNECTORS:2500 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度: (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0. 1~1. 3N{10~130gf}

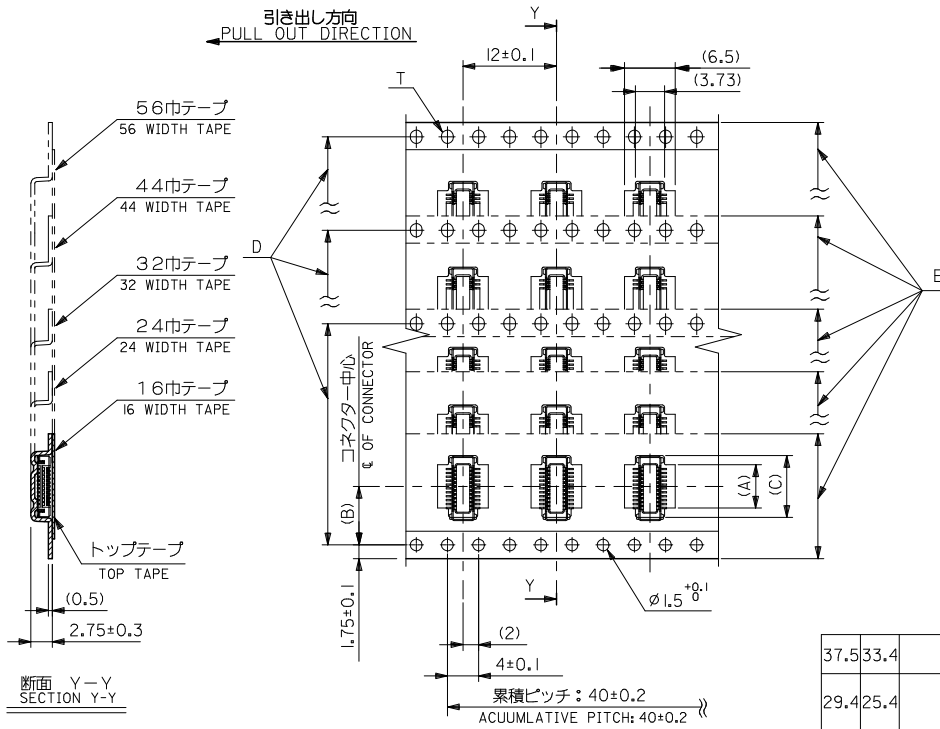
尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ:ポリプロピレン (PP)
CARRIER TAPE:POLYPROPYLENE(PP)
トップテープ:PET, PE, PEF
TOP TAPE:PET,PE,PEF
リール:ポリスチレン (PS) <リサイクル材を含む>
REEL: POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は55650-***8の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***8

MATERIAL 材料	注記参照 SEE NOTES	REVISED EC NO: J2009-0552 DRAWN BY: J2008/12/04 CHKD: THARYAMA APPR: NIKITA 2008/12/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
FINISH 仕上げ	注記参照 SEE NOTES		10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSD TAPE PACKAGE FOR 55650-***81 -LEAD FREE-		
WIPE RANGE 適用電線範囲			10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
INS. RANGE 被覆外径			30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	DOCUMENT NO. SD-55650-014		
			ANGULAR	±3 °	MATERIAL NO. SEE SHEET 2		SHEET NO. 1 OF 2		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1



37.5	33.4	32±0.3	28.4	20.45	14.2	18.05	55650-0788	70
				17.95		15.55	55650-0688	60
29.4	25.4	24±0.3		15.45	11.5	13.05	55650-0588	50
				12.95		10.55	55650-0488	40
				10.45		8.05	55650-0388	30
21.4	17.4	16±0.3		7.95	7.5	5.55	55650-0288	20
G	F	E	D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-**88

MATERIAL 材料	注記参照 SEE NOTES	REVISED J2009-0552 2008/12/04 DRW:YOSHIDAM 2008/12/04 CHKD:THARYAMA 2008/12/08 APPR:NIKIITA 2008/12/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
FINISH 仕上げ	注記参照 SEE NOTES		10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSED TAPE PACKAGE FOR 55650-**81 -LEAD FREE-		
WIPE RANGE 適用電線範囲			30 OVER ±0.3	ANGULAR ±3°	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
INS. RANGE 被覆外径			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO.	DOCUMENT NO. SD-55650-014	SHEET NO. 2 OF 2

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Rev. D 2004/04/02

EN-02JA(021)